Messrs. Digi-Key

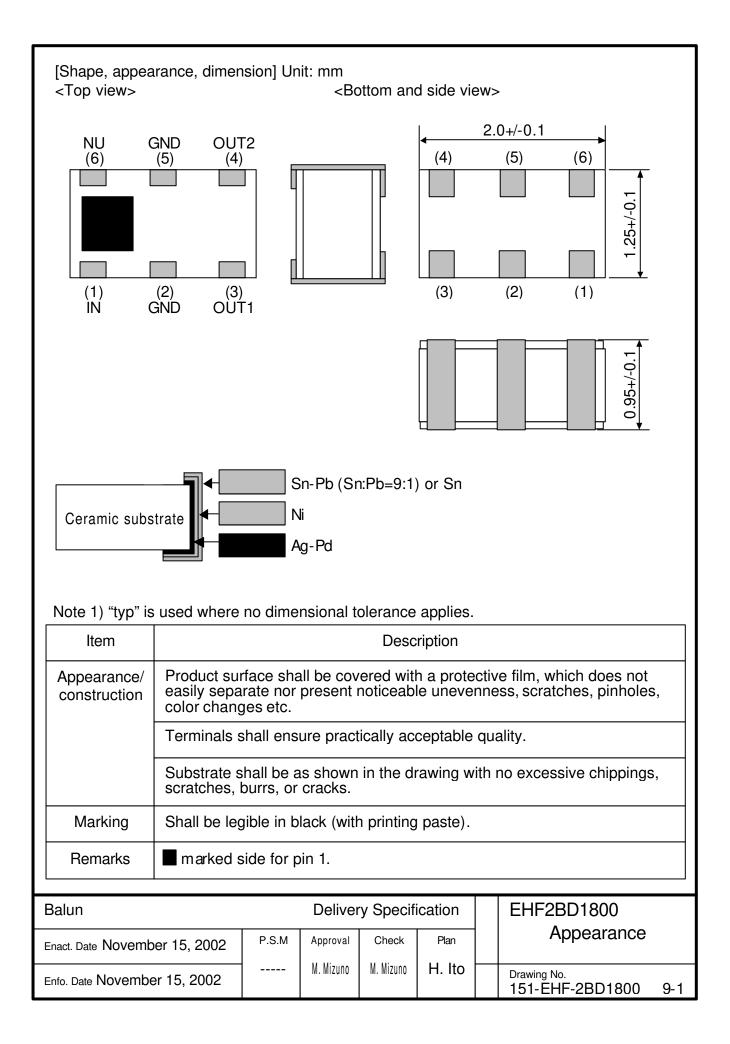
Issue No. : PC-02-061 Date of issue : November 15, 2002 Classification : ■ New □ Change □ Renewal

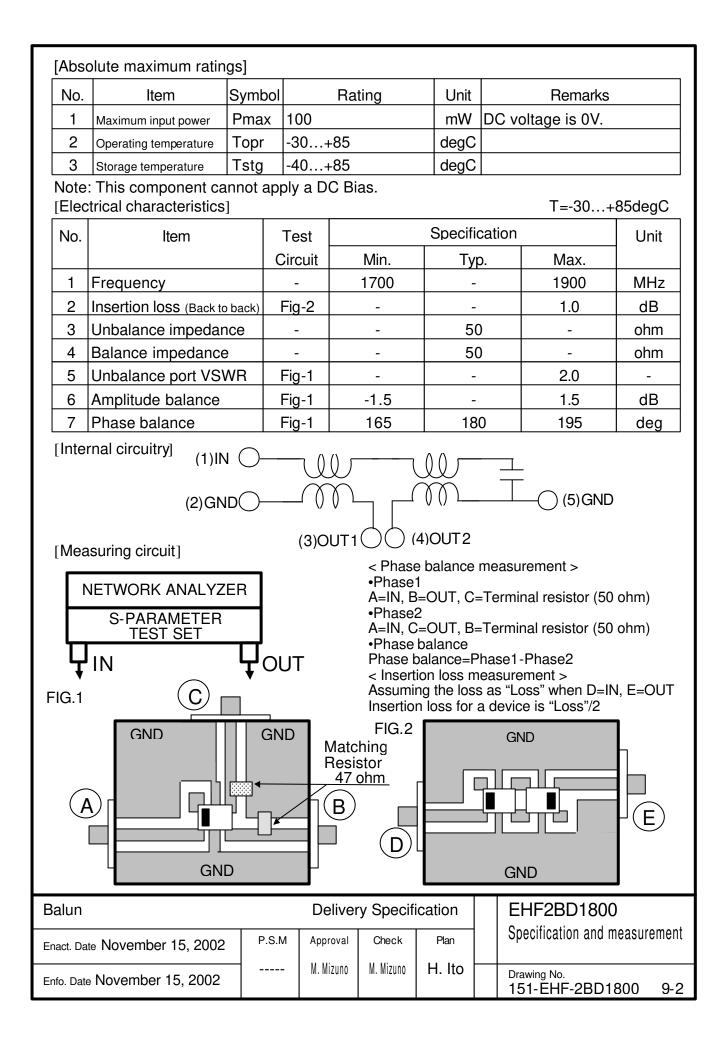
Delivery Specification

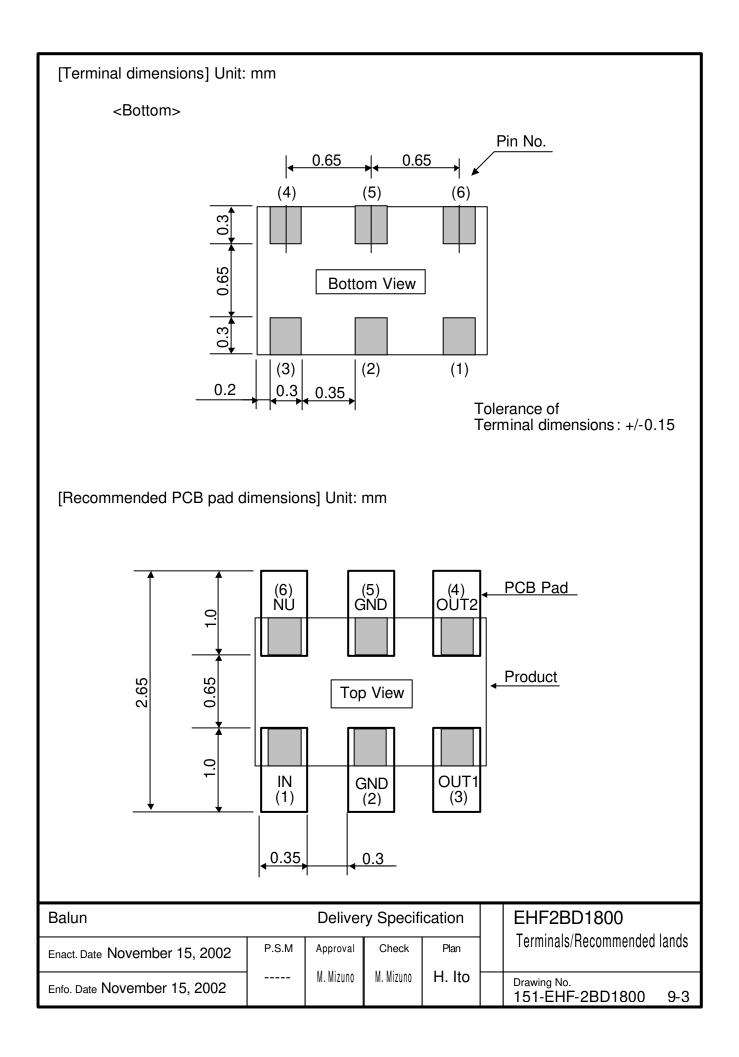
| Product Description | : Balun |
|------------------------|---|
| Product Part Number | : EHF2BD1800 |
| Classification of Spec | : Individual Product Specification |
| Applications | : Cellular phone |
| | For other applications, contact the undersigned in advance. |
| Term of Validity | : November 14, 2007 from the date of issue. |

| CUSTOMER USE ONLY | Receipt Record#: | |
|---|------------------|--|
| This was certainly received by us. 1(one) copy is being returned to you. | Date of receipt: | |
| | Received by: | |
| | Title: Dept.: | |

| Matsushita Electronic Components Co., Ltd. | | |
|---|---------------|--------------------------|
| Network Device Company | Prepared by | : H. Ito |
| Module Strategic Business Unit | Checked by | : M. Mizuno |
| Engineering Group HFD Team | | |
| 992-1 Aiba Ohno-cho Ibi-gun Gifu 501-0598 JAPAN | Authorized by | : M. Mizuno |
| Tel: +81-0585-36-2322 | Title | : Manager of Engineering |
| Fax: +81-0585-36-2344 | | . Manager er Engineering |







| [Quality characteristic | s] | | | | | | |
|--|---|--|--|--|--|--|--|
| Test item | Test condition | Judgment criteria | | | | | |
| High temperature | +85degC, 1000h | No abnormality shall be observed in | | | | | |
| Low temperature | -40degC, 1000h | appearance or | | | | | |
| High-temperature high-humidity storage | +60degC, 90%RH, 1000h | electrical characteristics. | | | | | |
| Pressure Pot | +121degC, 99%RH, 2.026x10 ⁵ Pa, 100h | characteristics. | | | | | |
| Temperature cycling | -40+85degC, Each 30 min., 200cy | | | | | | |
| Vibration | 10500Hz, 10G, in each direction of XYZ, 2h30min. | | | | | | |
| Impact | 100G, 6mS, Half sinusoidal wave, in each direction of XYZ, 3 times | | | | | | |
| Shock (Drop) | 1.8m, 6 facesx6cy(36 times with 100g Dummy Load) | | | | | | |
| Electro static discharge | 200pF, 0 ohm, +/-200V, Each 5 times | | | | | | |
| Soldering heat resistance | Manual hot gas: 260+/-10degC, 30 sec., 2 times | Over 90% of the terminal | | | | | |
| | Soldering iron: 260+/-10degC, 3 sec., 2 times | surface shall be covered with solder. | | | | | |
| | Reflow: 260degC peak, 2 times | | | | | | |
| Solder ability | Solder bath: 235+/-5degC, 2 sec. | Over 95% of the terminal | | | | | |
| | Reflow: 230degC | surface shall be covered with solder. | | | | | |
| Board warping | Assemble this component on a PC board with 0.8mm thickness using the recommended soldering condition shown below, and apply a bending force of 3mm warping at a rate of 1mm/sec. 5 seconds and 5 times. | There should not be any cracks in the component or solder joints, no abnormality in electrical characteristics. | | | | | |
| Terminal removal | Solder a component on a PC board using the recommended then press the component sideways at 1mm/sec. Destruction lin | | | | | | |
| Seating plane co-planarity | Within 0.1mm | | | | | | |
| < Recommended sold Diagram1 Shown b degC 250 230 230 200 170 140 | below is a recommended reflow soldering conditio | | | | | | |
| 30~60 sec. 60~180 sec. Time | | | | | | | |
| BalunDelivery SpecificationEHF2BD1800 | | | | | | | |
| Enact. Date November 15, 2002 P.S.M Approval Check Plan Quality Characte | | | | | | | |
| Enfo. Date November 15, 20 | ^{g No.} EHF-2BD1800 9-4 | | | | | | |

[Cautions for use]

- (1) Operating a product over the maximum rating for even a moment may result in a product failure or breakage. Never use a product in such a condition that it may cause a safety problem.
- (2) Opening or short-circuiting the product terminals or inserting a product in the reverse orientation while power is being supplied may cause a breakage. Always avoid such circumstances.
- (3) Operations in a corrosive gas atmosphere or improper environments such as hightemperature, high-humidity or dewy conditions may lead to product performance deterioration, a breakage, a change in appearance etc. Please avoid such conditions, as they are unsafe.
- (4) Always ground the soldering iron or soldering bath used for assembly operation to avoid any excessive voltage applied to a product.
- (5) After soldering with solder bridges, incomplete soldering or in the reverse orientation, supplying power may result in a product breakage. Please confirm the soldered condition before supplying power to the product.
- (6) Excessive stress on the terminals may cause a contact failure or performance deterioration. Please use caution.
- (7) Please provide a fail-safe provision in the product you design by taking any failure of our product into consideration.
- (8) This product does not include a DC-cutting device. Application of a DC voltage between the Balance port and the Unbalance port may cause product deterioration or breakage.
 - * If any question arises about the safety of this product, please contact us immediately with a request for an engineering examination.

[Remarks]

- *1: All of the materials used in this product are those listed as the existing chemical substances based on the "Law for examination and regulation of manufacture of chemical substances".
- *2: The production process of this product does not use any ozone-depleting chemicals (OZC) regulated by the Montreal Protocol.
- *3: Validity of this specification is 5 years from the date of issue, but the validity is considered on going unless any changes are made.

| Balun | Delivery Specification | | | EHF2BD1800 | |
|-------------------------------|------------------------|-----------|-----------|------------|------------------------------------|
| Enact. Date November 15, 2002 | P.S.M | Approval | Check | Plan | Cautions |
| Enfo. Date November 15, 2002 | | M. Mizuno | M. Mizuno | H. Ito | Drawing No. 151-EHF-2BD1800 9-5 |

[Packaging materials] 1. Materials 1)

- Embossed carrier tape (Refer to the attachment)
 Top tape: Anti-static

- 3) Packaging box (Refer to the attachment)4) Packaging tape, carrier-securing adhesive tape
- 2. Specification

| | - | | | | | | | |
|---|--|-----------|--------------------------|----------------|------------------|----------------------------------|----------------------------------|--|
| No. | Item | Condition | | | | | | Remarks |
| 1 | Reel outer diameter | Refer t | the att | | | | | |
| 2 | Reel inner diameter | Refer t | to the att | | | | | |
| 3 | Reel inner width | Refer t | the att | <u>achment</u> | | | | |
| 4 | Quantity in a reel | 4000 p | <u>ieces/re</u> | el | | | | |
| 5 | Taping direction | | | | | | ling direction ngs facing up) | |
| 6 | Top tape attachment position | Top tape | pe attachm e edge mus | | • | 5.5mm Emb | tape | Tape breaks force. Min. 10N Top cover tape strength. Min. 10N Tape peel force. 0.11.0N Tape peel angle. 165180degree Reel weight. Max 1500g |
| 7 | Label attachment position | | | Label | ₩ 1 | ape unreelii | ng direction | Indicated Item Pat No., Lot No. Quantity, Maker Country of Origin |
| 8 | Tape leader part and tape ending part | 20 | part Prod | | 1 00~150mm, 1 | Leader | Top tape | |
| 9 | 9 Missing products No missing products shall be allowed. | | | | | | | |
| | | | | | | | 84000 pieces/box(Max) | |
| | | | | | | BD1800 ging specification 1 | | |
| Enfo. Date November 15, 2002 M. Mizuno M. Mizuno H. Ito Drawing 151-E | | | | | | _{∿o.} HF-2BD1800 9-6 | | |

